

PRESS RELEASE

New die attach adhesives for chips / DELO presents new solutions for semiconductor manufacturers at the ECTC

Windach / Melville, 4 May 2009: DELO® Industrial Adhesives presents newly developed die attach adhesives for semiconductor packaging at the ECTC (Electronic Components and Technology Conference) semiconductor fair taking place in San Diego from May 26 – 29 2009.

These new solvent-free adhesives ensure that sensitive chips are reliably fixed in the leadframe package at high temperatures. Chip packaging is becoming ever more demanding - if the chip package is soldered without using lead, increased temperatures of up to +260 °C (+500 °F) may occur. This means that the adhesive must withstand these high temperatures for short periods of time. Moreover, chip packages are getting smaller, and must be protected against humidity. Comprehensive die shear tests in DELO's laboratories prove that its new adhesives reliably fix chips even during storage at +85 °C (+185 °F) / 85 % relative humidity for 168 hours, and subsequent simulated soldering at temperatures of up to +260 °C (+500 °F).

The new one-component DELO®-MONOPOX® chip adhesives are suitable for various chip sizes and therefore multiple applications, especially in situations where temperature and stress-sensitive parts are used, such as in sensors, signal processors or control chips.

One further advantage is their fast curing time, allowing short cycle times and a reduction in processing costs. Moreover, the adhesives show very low water absorption rates, dispense readily and have a long processing time in production.

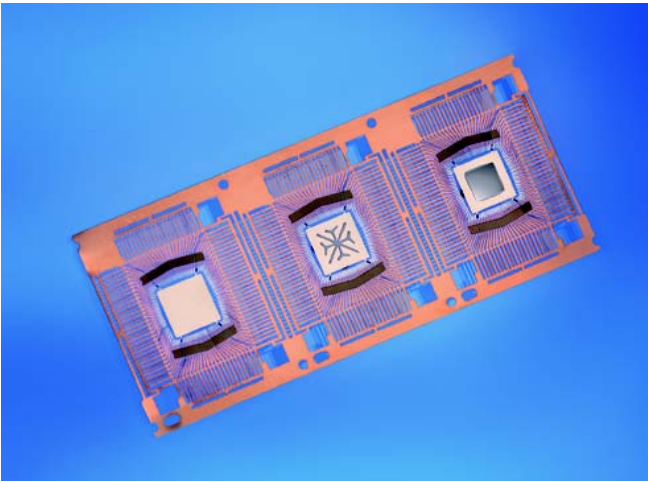
Further information and a free brochure on "Die Attach Solutions" can be obtained by sending an e-mail to Jennifer.Bader@DELO.us.

About DELO:

DELO is a leading manufacturer of industrial adhesives, with its head office near Munich/Germany. In the 2008/09 fiscal year the company's 230 employees generated sales of 30 million Euros. The company supplies special adhesives and associated equipment tailored to applications in many areas of business, from electronics to the chip card and automotive industry, as well as in glass and plastic design. DELO's customers include Bosch, Daimler, Festo, Infineon, NXP and Siemens. DELO has a worldwide network of distributors and sales partners.

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For high resolution images please contact: Jennifer.Bader@DELO.us